



AOS NON-SILICONE HTC 80

Product Code: 52050

TECHNICAL DATA SHEET



Product Description

AOS Non-Silicone HTC 80 (High Thermal Conductivity) Heat Sink Compound has been designed for low bond line performance in a non-silicone and non-metal filled thermal grease.

- AOS 52050 is formulated with organic renewable “green” fluid technology; the product will never phase separate and resists pump out. Although a highly filled system, 52050 will easily spread into a thin film
- As with our entire line of Heat Sink Compounds, the AOS technical staff can modify AOS Non-Silicone HTC to meet your exacting specifications.

Typical Properties

<u>Property</u>	<u>Value</u>	<u>Test Method</u>
Consistency (Penetration, worked, 60x)	250 - 300	ASTM D-217
Specific Gravity , @ 25°C	2.6	ASTM D-70
Bleed , @ 200°C, 24 Hrs., %/Wt	0.01	FTM-321 MODIFIED
Evaporation , @ 200°C, 24 Hrs., %/Wt.	0.1	FTM-321 MODIFIED
Thermal Conductivity , @ 36°C W/m-K	3.8	ASTM D 5470-06
Thermal Resistance , @ 50 °C °C/W	0.0671	Oracle TTV model 270-7806-01
Electrical Properties		
Dielectric Strength, 0.05” gap, V/mil	351	ASTM D-149
Dielectric Constant, 25°C @ 1,000 Hz	4.92	ASTM D-150
Dissipation Factor, 25°C @ 1,000 Hz	0.0032	ASTM D-150
Volume Resistivity, ohm-cm	1.0 x 10 ¹³	ASTM D-257
Operating Temperature Range	-40°C to 200°C	
Flow Rate grams/min.	2 - 3	AOS Method #1
Appearance	Dark Gray Paste	

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